

ABSTRACT OF THE DISCLOSURE

According to one aspect of the invention, an electronic assembly and a method for constructing an electronic assembly are provided. Insulating bodies interconnect a heat sink plate, or support plate, and a plurality of support members to form a heat sink assembly. The heat sink assembly is placed on a circuit board along with a semiconductor package. The entire circuit board is heated to solder the heat sink assembly and the semiconductor package to the circuit board. The insulating bodies thermally separate the heat sink plate and the support members so that heat is not conducted from the support members to the heat sink plate, and the heat sink plate and semiconductor package may be attached to the circuit board in a one-step heating process.